

Title (en)

PRINTED CIRCUIT BOARD AND A METHOD FOR PRODUCING SUCH A PRINTED CIRCUIT BOARD

Title (de)

LEITERPLATTE UND VERFAHREN ZUR HERSTELLUNG EINER SOLCHEN LEITERPLATTE

Title (fr)

CARTE DE CIRCUIT IMPRIMÉ ET PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUIT IMPRIMÉ

Publication

**EP 3494765 A1 20190612 (DE)**

Application

**EP 17735506 A 20170704**

Priority

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Abstract (en)

[origin: WO2018024426A1] The invention relates to a printed circuit board, preferably for use in a fuel fill-level sensor and in a fuel fill-level measuring system, comprising conducting tracks (4, 5) formed on two sides of a ceramic substrate (2), wherein the ceramic substrate (2) has at least one metallized hole (3) for through-connection, which hole connects the conducting tracks (4, 5) to each other. The hole (3) of the sintered ceramic substrate (2) is filled with a metal-containing sintering paste introduced under compression pressure. In the fully sintered state, said sintering paste enters into at least one integral bond with the ceramic substrate (2) and completely fills the hole. The invention further relates to a method for producing such a printed circuit board.

IPC 8 full level

**H05K 3/12** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP KR US)

**H05K 1/0306** (2013.01 - US); **H05K 1/116** (2013.01 - US); **H05K 3/0094** (2013.01 - US); **H05K 3/3485** (2020.08 - US); **H05K 3/4061** (2013.01 - EP KR); **H05K 1/092** (2013.01 - EP KR); **H05K 3/1225** (2013.01 - EP KR); **H05K 3/1291** (2013.01 - EP KR); **H05K 2201/09481** (2013.01 - EP KR); **H05K 2201/09563** (2013.01 - EP KR); **H05K 2201/10151** (2013.01 - US); **H05K 2203/0126** (2013.01 - EP KR); **H05K 2203/1438** (2013.01 - EP KR); **H05K 2203/1476** (2013.01 - EP KR)

Citation (search report)

See references of WO 2018024426A1

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